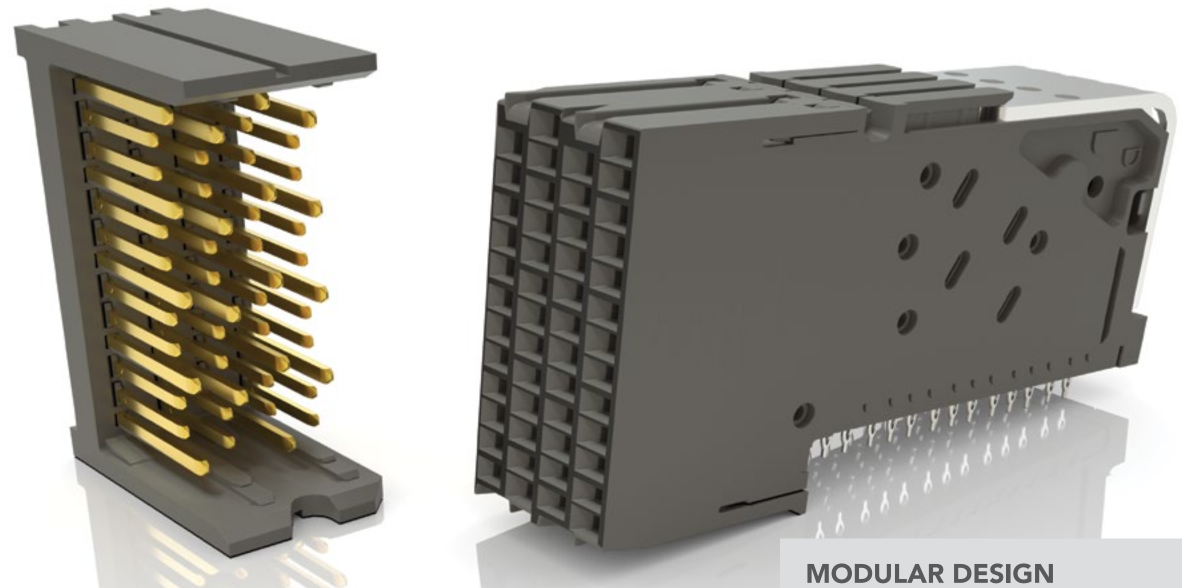
XCede HD

HIGH-DENSITY BACKPLANE HEADERS & SOCKETS

(1.80 mm) .071" PITCH

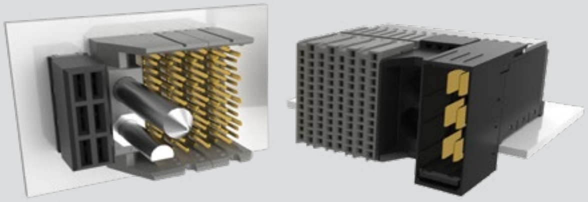
16 Gbps



FEATURES & BENEFITS

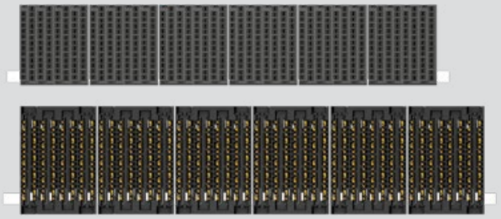
- Small form factor and modular design provides significant space-savings and flexibility
- High-performance system
- Up to 84 differential pairs per linear inch
- 3, 4 and 6-pair designs on 4, 6 and 8 columns
- Integrated power, guidance, keying and end walls available
- 85 Ω and 100 Ω options
- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane
- Press-fit extraction and insertion tool options; please visit samtec.com/tooling for details

MODULAR DESIGN



Signal, Power & Keying / Guidance options can be customized in any configuration

HIGH-DENSITY, SMALL FORM FACTOR



XCede® HD
Up to 84 pairs per linear inch

Traditional Backplane
Up to 76 pairs per linear inch

(Both shown with six 4-pair, 8 column receptacles)

KEY SPECIFICATIONS

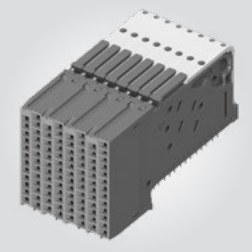
PITCH	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE
1.80 mm	LCP	Phosphor Bronze (HDTM Series) Copper Alloy (HDTF & HPTS Series)	Au or Sn over 50 µ" (1.27 µm) Ni	-40 °C to + 105 °C (HDTX Series)

XCede HD

(1.80 mm) .071" PITCH • HIGH-DENSITY BACKPLANE RECEPTACLE

HDTF	PAIRS PER COLUMN	NO. OF COLUMNS	PLATING	RA	WAFERS	IMPEDANCE
	–3, –4, –6	**–04, –06, –08**	**–S** = 30 µ" (0.76 µm) Gold on Contact Area, Matte Tin on Tail		**–LC** = Standard **–HS** = High-Speed	**–100** = 100 Ω **–085** = 85 Ω

HDTF
Board Mates:
HDTM

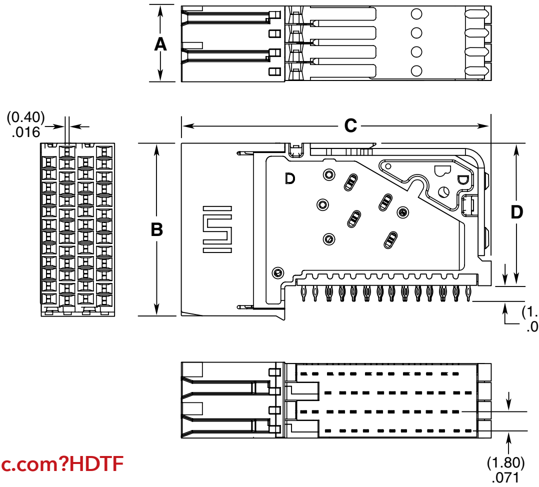


ALSO AVAILABLE

Power and keying/guidance modules also are available but require a single customizable BSP product. Contact HSBP@samtec.com.

NO. OF COLUMNS	A
–04	(7.2) .28
–06	(10.8) .42
–08	(14.4) .57

PAIRS PER COLUMN	B	C	D
–3	(12.8) .50	(26.0) 1.02	(9.8) .386
–4	(16.4) .64	(29.4) 1.16	(13.5) .53
–6	(23.6) .93	(36.6)1.44	(20.7) .81

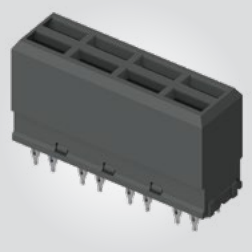


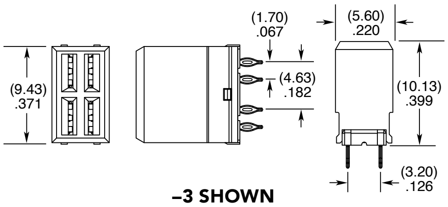
View complete specifications at: samtec.com?HDTF

(3.20 mm) .126" PITCH • HIGH-DENSITY BACKPLANE POWER MODULE

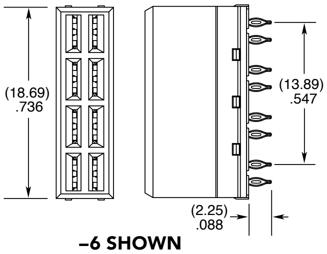
HPTS	BODY HEIGHT	PLATING	D	ORIENTATION
	Based on Pair Count of Signal Modules (HDTF Series). **–3** = For use with 3 pair HDTF Series **–4** = For use with 4 pair HDTF Series **–6** = For use with 6 pair HDTF Series	**–S** = 30 µ" (0.76 µm) Gold on Contact Area, Matte Tin on Tail		**–VT** = Vertical

HPTS
Mates with:
BSP
(See HDTF for more information.)

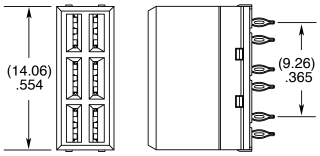




–3 SHOWN



–6 SHOWN



–4 SHOWN

View complete specifications at: samtec.com?HPTS

Notes:
Some lengths, styles and options are non-standard, non-returnable.
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